

ABSTRACT

In a semiconductor device of a structure comprising a thin semiconductor element bonded to a reinforcing plate with a bonding layer of a predetermined thickness, resin binder used for forming the bonding layer contains fillers including first filler, which has a diameter generally equal to a target thickness of the bonding layer to be adjusted to a value within a range of proper thickness (from 25 μ m to 200 μ m). This can maintain the bonding layer within the range of proper thickness when the semiconductor element is bonded to the plate, and ensure on-board mounting reliability of the semiconductor device.